ruhlamat – market-leading, innovative systems at affordable prices

The smart card market is characterised by strong competition and falling prices for components. This requires a higher level of automation and increased efficiency, without compromising quality and precision. Face these mounting challenges head-on with innovative machines and systems designed by ruhlamat to perform in the most demanding production environments.

Our affordable and industry-proven machine solutions provide the speed, quality and economy that will help you to sustain and maximise profitability in the future. We offer sophisticated, high-quality machines for the chip module production, ranging from encapsulation, testing and encoding of IC modules to glue tape lamination of module tapes.

ruhlamat – customised machine solutions for

- Chip Module Production
- RFID Inlay Production
- Card Production
- Card Personalisation
- Card Quality Control
- Passport Personalisation
- Passport Quality Control
- Special Machinery
ruhlamat - PowerTest
Chip Module Testing/Initialisation

Benefits and features:
- Real-time system for chip module test, initialisation and pre-personalisation
- Contact, contactless and Dual Interface modules can be processed on one machine
- High-speed transport system, including reject hole detection at input and output
- Reject hole punch for faulty chip modules
- Modular design and graphic user interface
- Open platform for integration of customer test hardware and software

The PowerTest is a sophisticated chip module test and encoding system for 35 mm tape.

ruhlamat - GTL 700
Glue Tape Lamination

Benefits and features:
- Highest yield, maximum machine uptime and short product changeover times lead to very low cost of ownership
- High flexibility for all IC module types and sizes, including Dual Interface
- In-house tool manufacturing, customised punching tool design on request
- Stand-alone system or integration into production line

The GTL700 is a highly reliable and flexible module for 35 mm lamination of chip modules in preparation for the hot melt implanting process.

ruhlamat - PowerSeal
Chip Module Encapsulation

Benefits and features:
- FILL or DAM & Fill process
- Programmable movement of dosing heads
- Heating of module tape & dosing heads
- Visual process control
- Additional globe-top form inspection
- Competitiveness by combining a substantially increased throughput at a very attractive price level

The GTL700 is a highly reliable and flexible scanner for 35 mm lamination of chip modules in preparation for the hot melt implanting process.